

**IN THE CLAIMS:**

A status of all the claims of the present Application is presented below:

1. (Currently amended) An electronic circuit assembly test apparatus, comprising:  
a support member having a plurality of probes, each probe adapted to contact a corresponding test area of an electronic circuit assembly; and  
a probe assembly coupled to the support member, the probe assembly having a plurality of probes configured to contact test areas of the electronic circuit assembly different than the test areas contacted by the probes of the support member, wherein a spacing density of the probes of the probe assembly is greater than a spacing density of the probes of the support member.
2. (Original) The apparatus of Claim 1, wherein the spacing density of the probes of the probe assembly corresponds to test areas of an integrated circuit.
3. (Original) The apparatus of Claim 1, wherein the probe assembly is adapted to move laterally relative to the support member.
4. (Original) The apparatus of Claim 1, wherein the probe assembly comprises at least one alignment guide adapted to cooperate with an alignment guide disposed on the electronic circuit assembly.
5. (Original) The apparatus of Claim 1, wherein the probe assembly comprises at least one limiter adapted to limit movement of the probes of the probe assembly toward the electronic circuit assembly.
6. (Original) The apparatus of Claim 1, wherein the probe assembly is movably coupled to the support member to provide non-lateral movement of the probe assembly relative to the support member.

7. (Original) The apparatus of Claim 1, wherein the probes of the probe assembly comprise spring-biased probes.

8. (Original) The apparatus of Claim 1, further comprising at least one spring disposed between the probe assembly and the support member.

9. (Currently amended) An electronic circuit assembly test apparatus, comprising:  
first probe means coupled to a support member and adapted to contact corresponding test areas on an electronic circuit assembly;  
support means coupled to the support member; and  
second probe means coupled to the support means and configured to contact test areas on the electronic circuit assembly different than the test areas contacted by the first probe means, the second probe means having a spacing density of probes greater than a spacing density of probes of the first probe means.

10. (Original) The apparatus of Claim 9, wherein the support means is movably coupled to the support member.

11. (Original) The apparatus of Claim 9, wherein the support means is coupled to the support member to enable lateral movement of the support means relative to the support member.

12. (Original) The apparatus of Claim 9, further comprising means for aligning the second probe means with corresponding test areas of the electronic circuit assembly.

13. (Original) The apparatus of Claim 9, further comprising means for limiting travel of the second probe means toward the electronic circuit assembly.

14. (Withdrawn) An electronic circuit assembly test apparatus, comprising:  
a plurality of probes coupled to a support member, the probes adapted to contact corresponding test areas of an electronic circuit assembly; and

a probe assembly movably coupled to the support member, the probe assembly comprising a plurality of probes adapted to contact corresponding test areas of the electronic circuit assembly.

15. (Withdrawn) The apparatus of Claim 14, wherein the probe assembly is movably coupled to the support member to enable lateral movement of the probe assembly relative to the support member.

16. (Withdrawn) The apparatus of Claim 14, wherein the probe assembly is movably coupled to the support member to enable non-lateral movement of the probe assembly relative to the support member.

17. (Withdrawn) The apparatus of Claim 14, wherein the probe assembly comprises at least one limiter adapted to limit travel of the probes of the probe assembly toward the electronic circuit assembly.

18. (Withdrawn) The apparatus of Claim 14, wherein the probe assembly comprises at least one alignment guide adapted to align the probes of the probe assembly with corresponding test areas of the electronic circuit assembly.

19. (Withdrawn) An electronic circuit assembly test apparatus, comprising:  
a support member;  
a test probe assembly having a plurality of probes adapted to contact corresponding test areas of an electronic circuit assembly; and  
a float assembly disposed between the test probe assembly and the support member.

20. (Withdrawn) The apparatus of Claim 19, wherein the float assembly is adapted to bias the test probe assembly away from the support member.

21. (Withdrawn) The apparatus of Claim 19, wherein the float assembly is adapted to enable lateral movement of the test probe assembly relative to the support member.

22. (Withdrawn) The apparatus of Claim 19, wherein the float assembly is adapted to enable non-lateral movement of the test probe assembly relative to the support member.

23. (Withdrawn) The apparatus of Claim 19, further comprising at least one limiter adapted to limit movement of the probes of the test probe assembly toward the electronic circuit assembly.

24. (Withdrawn) The apparatus of Claim 19, further comprising at least one alignment guide adapted to align the probes with the corresponding test areas of the electronic circuit assembly.

25. (Withdrawn) The apparatus of Claim 19, wherein the test probe assembly comprises at least one alignment pin adapted to cooperate with the electronic circuit assembly to align the probes with the test areas of the electronic circuit assembly.

26. (Withdrawn) The apparatus of Claim 19, wherein the test probe assembly comprises at least one stop adapted to limit movement of the probe assembly toward the electronic circuit assembly.

27. (Withdrawn) The apparatus of Claim 19, wherein the float assembly comprises at least one spring disposed between the test probe assembly and the support member.

28. (New) An electronic circuit assembly test apparatus, comprising:  
a support member having a plurality of probes configured to contact a first plurality of test areas of an electronic circuit assembly; and  
a probe assembly coupled to the support member, the probe assembly having a plurality of probes configured to contact a second plurality of test areas of the electronic circuit assembly, wherein the probes of the probe assembly are spaced to accommodate a spacing density of the second plurality of test areas greater than a spacing density of the first plurality of test areas.
29. (New) The apparatus of Claim 28, wherein the probe assembly is adapted to move laterally relative to the support member.
30. (New) The apparatus of Claim 28, wherein the probe assembly comprises at least one alignment guide adapted to cooperate with an alignment guide disposed on the electronic circuit assembly.
31. (New) The apparatus of Claim 28, wherein the probe assembly comprises at least one limiter adapted to limit movement of the probes of the probe assembly toward the electronic circuit assembly.
32. (New) The apparatus of Claim 28, wherein the probe assembly is movably coupled to the support member to provide non-lateral movement of the probe assembly relative to the support member
33. (New) The apparatus of Claim 28, further comprising at least one spring disposed between the probe assembly and the support member